

Final Product/Process Change Notification Document #: FPCN22288Y

Issue Date: 2 August 2018

- 1.1 C C C		SEMCO substrates supplier Discontinuance. Qualification of Alternate supplier				
Title of Change:		SEMCO substrates supplier Discontinuance – Qualification of Alternate supplier.				
Proposed first ship date:		1 January 2019				
Contact informa	ation:	Contact your local ON Semiconductor Sales Office or < <u>ivo.rotthier@onsemi.com</u> > or < <u>Renato.NeypesJr@onsemi.com</u> >				
Samples:		Contact your local ON Semiconductor Sales Office or < PCN.samples@onsemi.com > Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.				
Additional Relia	bility Data:	Contact your local ON Semiconductor Sales Office or <pre>phine.guevarra@onsemi.com</pre>				
Type of notificat	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days delivery of this notice. To do so, contact < PCN.Support@onsemi.com			unless an inquiry is made in writing within 30 days of		
Change Part Identification: Affected products will be identified by date code						
Change Categor	Change Category: ☐ Wafer Fab Change			Test Change Other		
Change Sub-Category(s): ☐ Manufacturing Site Addition ☐ Manufacturing Site Transfer ☐ Manufacturing Process Change ☐ Other: ☐ Datasheet/Product Doc change ☐ Shipping/Packaging/Marking ☐ Other:						
Sites Affected:		ON Semiconductor Sites: None		External Foundry/Subcon Sites: Amkor Technology Philippines P3		
Description and Purpose:						
This Final Change Notification announces the qualification of a newlead frame supplier, UMTC and Nanya substrate for ATP3 LFBGA products, at Amkor Technology Philippines Plant 3 for orderable part number, 0W888-002-XTP. Change also includes from Halogenated (HL832/AUS308) to non-Halogenated materials (HL832NXA/AUS308). This change is due to the substrate supplier Semco Tenting CSP discontinuance. This will allow more flexibility on lead frame management and prevent lead frame shortage issues.						
	Material	to be changed	Before Change Description	After Change Description		
	Lea	adframe	SAMSUNG HL832/AUS308	NANYA HL832NXA/ AUS308 UMTC HL832NXA/ AUS308		

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Reliability Data Summary:

QV DEVICE NAME: 0W888-02 **RMS**: 042835, 042622 **PACKAGE**: LFBGA 64

<u>Nanya</u>

Test	Specification	Condition	Interval	Results
HTSL	JESD22-A103	Ta= 150°C	1000 hrs	0/240
TC	JESD22-A104	Ta= -55°C to +125°C	1000 сус	0/240
uHAST	JESD22-A118	110°C, 85% RH, 18.8psig, unbiased	264 hrs	0/237
PC	J-STD-020 JESD-A113	MSL 3 @ 260 °C		0/480
SBS	AEC-Q100-010			0/30
PD	JESD22-B100, B108			0/30

<u>UMTC – Unimicron Technology Corporation</u>

Test	Specification	Condition	Interval	Results
HTSL	JESD22-A103	Ta= 150°C	1000 hrs	0/239
TC	JESD22-A104	Ta= -55°C to +125°C	1000 cyc	0/238
uHAST	JESD22-A118	110°C, 85% RH, 18.8psig, unbiased	264 hrs	0/231
PC	J-STD-020 JESD-A113	MSL 3 @ 260 °C		0/474
SBS	AEC-Q100-010			0/30
PD	JESD22-B100, B108			0/30

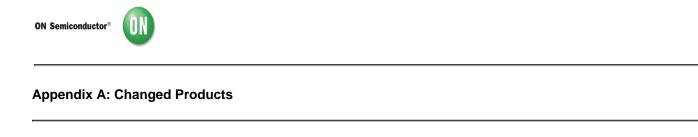
${\bf Electrical\,Characteristic\,Sum\,mary:}$

Electrical characteristics are not impacted.

List of Affected Part:

Part Number	Qualification Vehicle	
0W888-002-XTP	0W888-002-XTP	

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Product	Customer Part Number	Qualification Vehicle
0W888-002-XTP		0W888-002-XTP